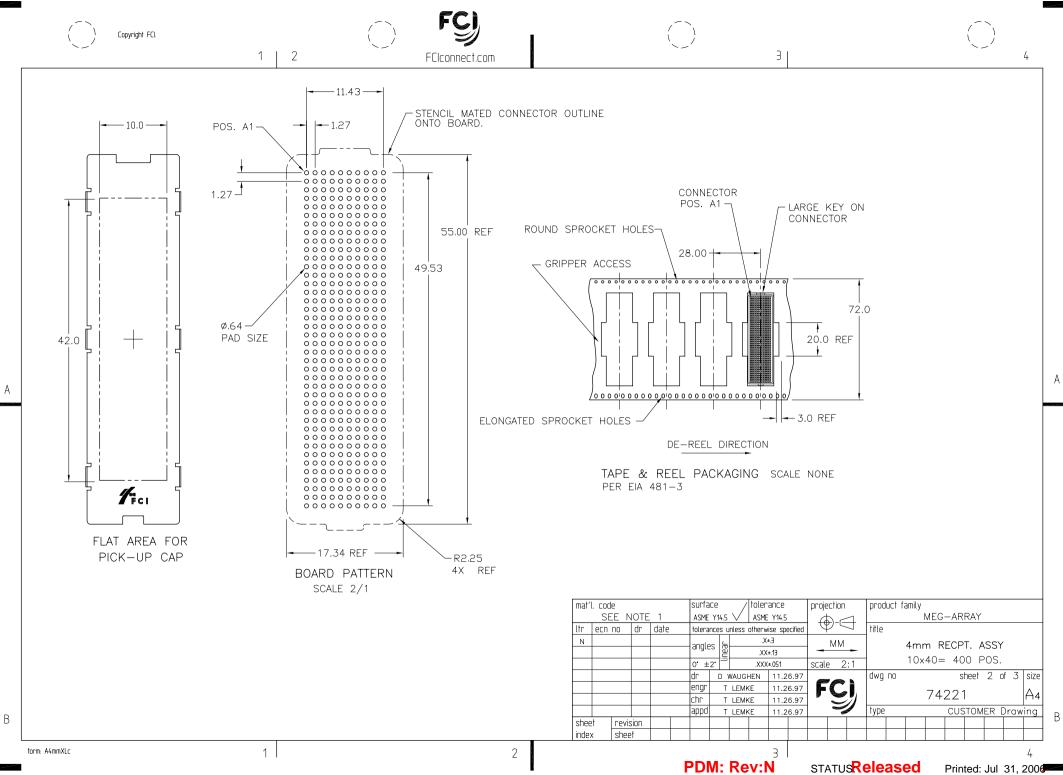


В



В





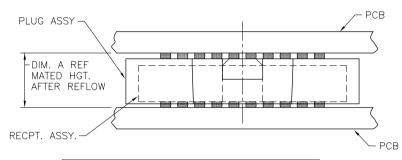
		1 2	FClconnect.com
PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74221-001	YES	15u" (.38um) Au OVER Ni	SnPb
74221-001LF			SnAgCu LEAD FREE 67
74221-101	YES	30 u" (.76um) Au OVER Ni	SnPb
74221-101LF			SnAgCu LEAD FREE 67
74221-201	YES	SEE NOTE 5.	SnPb
74221-201LF			SnAgCu LEAD FREE 6 7





- CONTACT: (SEE TABLE ON SHEET3) SOLDER BALL: (SEE TABLE ON SHEET3) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu
- (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) NO TIN\LEAD OR FLUX ABOVE TERMINAL SHOULDER.
- (5.)PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (6) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (7) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

1

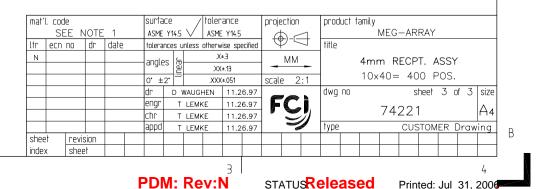


MATED HEIGHT TABLE				
DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N		
4.0	84740	74221		
10.0	84520	74221		

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

2



A

З

В